Proceedings of the

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The IITC is sponsored by the IEEE Electron Devices Society, whose goal is to provide a forum for professionals in semiconductor processing, academia and equipment development to present and discuss exciting new science and technology; and Semiconductor International is the media sponsor.

SESSION 1: PLENARY SESSION

Co-Chairs: Gary W. Ray, *Intel Corp.*
Kuniko Kikuta, *NEC Electronics Corp.*
Ivo Raaijmakers, *ASM International nv*

SESSION 2: 3-D SILICON

Co-chairs: Mike Shapiro, *IBM*
and Young-Chang Joo, *Seoul National University*

SESSION 3: POSTER I

SESSION 4: MATERIALS AND PROCESSING I
Co-chairs: Ivo Raijimakers, *ASM International*
and Kuniko Kikuta, *NEC Electronics*

SESSION 5: MATERIALS AND PROCESSING II

Co-chairs: Michael Armacost, *Applied Materials*
and Vincent Arnal, *STMicroelectronics*

SESSION 6: RELIABILITY I

Co-chairs: Tomoji Nakamura, *Fujitisu Labs.*
and Maureen Brongo, *Skyworks Solutions*

SESSION 7: POSTER II

SESSION 8: RELIABILITY II
Co-chairs: Scott List, *SRC*
and Shinichi Ogawa, *SELETE*

SESSION 9: SYSTEM-ON-CHIP
Co-chairs: Hector Sanchez, *Freescale Semiconductor*
and Gary Ray, *Intel Corporation*

SESSION 10: PROCESS INTEGRATION I
Co-chairs: Didier Louis, *CEA-LETI*
and Toshiaki Hasegawa, *Sony Corp.*